

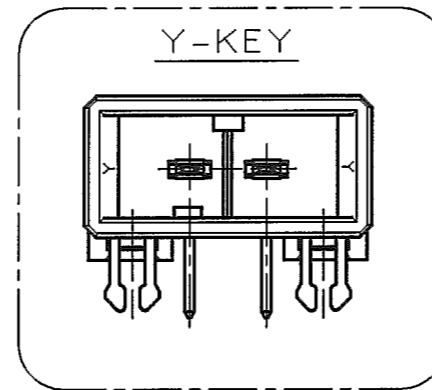
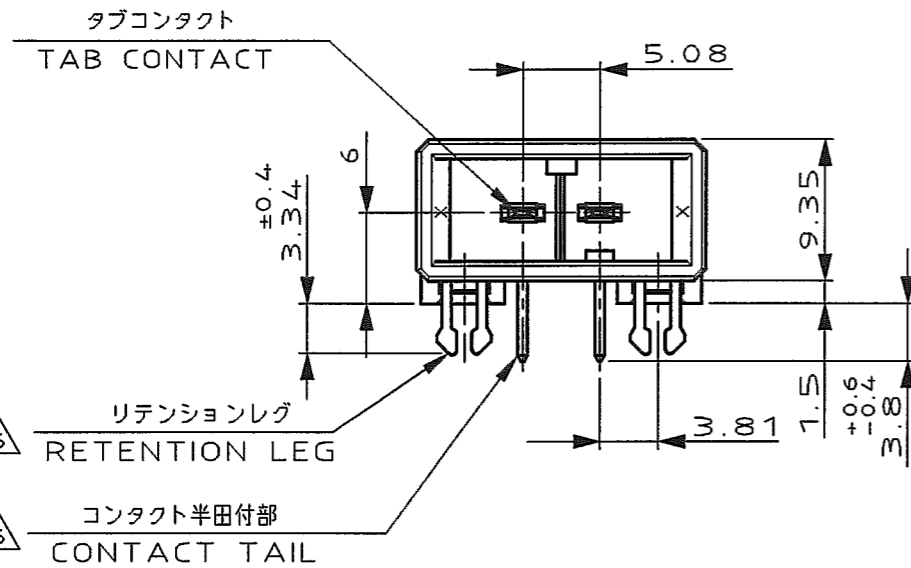
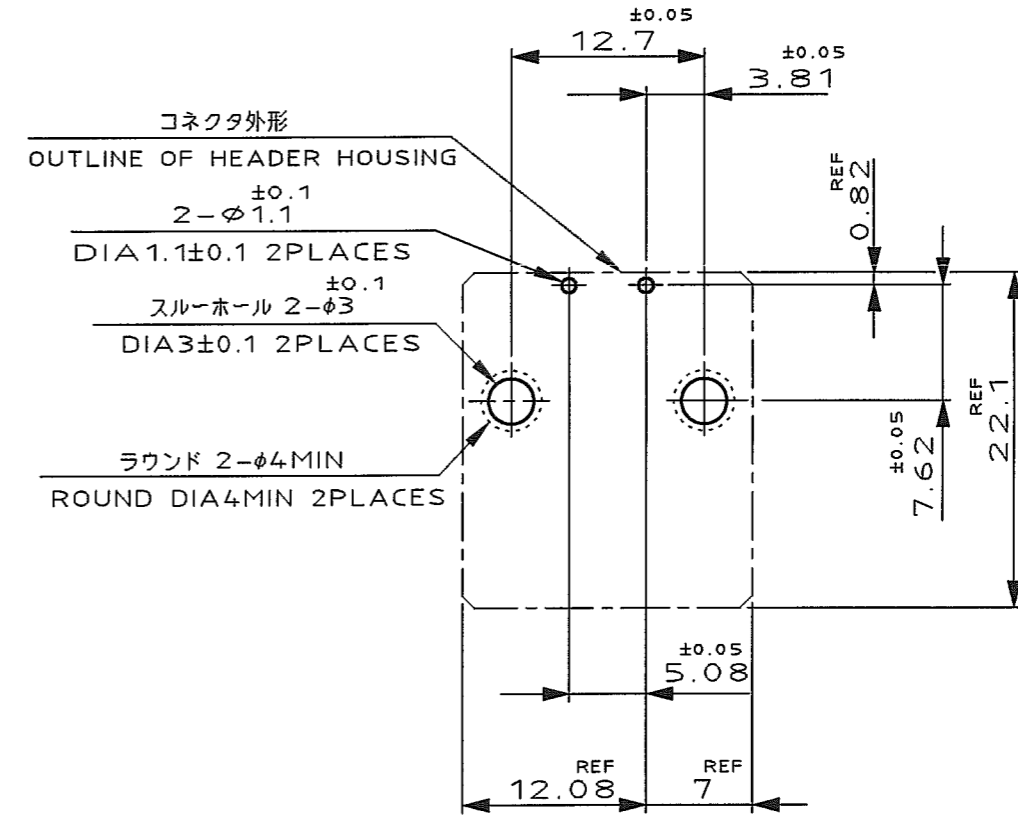
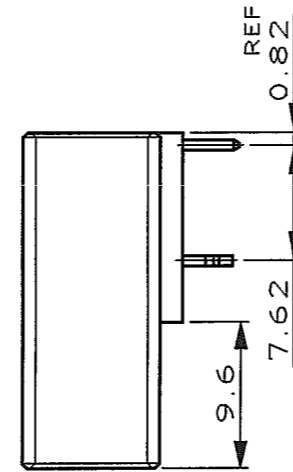
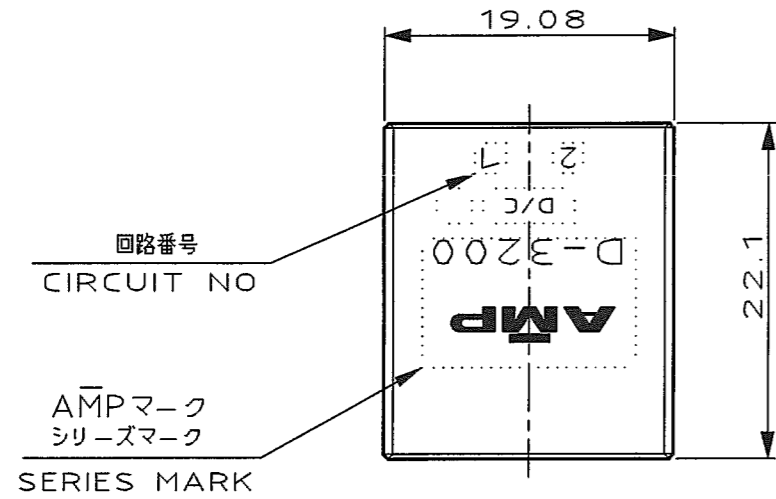
NUMBER 179276



METRIC

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST



推奨基板取付け穴寸法  
PC 基板厚: 1.6±0.1  
(非累積公差)  
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN  
PC BOARD THICKNESS: 1.6±0.1  
(NOT ACCUMULATE TOLERANCE)  
(CONNECTOR MOUNT SIDE)

NOTES

1. MATERIAL: HOUSING: GLASS FILED THERMO PLASTIC, POLYESTER  
CONTACT: COPPER ALLOY  
RETENTION LEG: COPPER ALLOY
2. FINISH (CONTACT AREA): 0.38μm MIN GOLD PLATING OVER Ni PLATING
3. FINISH (CONTACT AREA): 0.76μm MIN GOLD PLATING OVER Ni PLATING
4. FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
5. FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
6. FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL
7. OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI

注記

1. 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂  
コンタクト: 銅合金  
リテンションレグ: 銅合金
2. めっき: コンタクト: 全面Ni下地  
接触部: 0.38μm MIN金めっき
3. めっき: コンタクト: 全面Ni下地  
接触部: 0.76μm MIN金めっき
4. めっき: コンタクト: 全面Ni下地  
接触部: 2.0 μm MINスズめっき
5. めっき: リテンションレグとコンタクト半田付部  
ニッケル下地の上に半田めっき
6. めっき: リテンションレグとコンタクト半田付部  
ニッケル下地の上にスズめっき

△ OBSOLETE	6	4	2-179276-5	Y
	6	3	2-179276-3	Y
	6	2	2-179276-2	Y
	6	4	1-179276-5	X
	6	3	1-179276-3	X
	6	2	1-179276-2	X
(FINISH)		製品番号 (PART NO.)	KEY	

B2	REVISED PER ECO-11-005030	RK	HMR	22MAR11
LTR	REVISION RECORD	DR	CHK	DATE

WIRE RANGE	INSULATION DIA	NAME
mm (AWG - )	mmφ	2 POS SINGLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC D-3200
MATERIAL SEE NOTE 注記参照	FINISH SEE NOTE 注記参照	一般公差 (GENERAL TOLERANCE)
DR. 1 DEC 93 N. Matsubara	DE. 1 DEC 93 N. Matsubara	SIZE A3
CHK. S. MANABE	APP. S. MANABE	LOC J
		NUMBER C-179276
		SCALE 2-1
		REV. B2
		SHEET 1 OF 1

<b>STE</b> TE Connectivity			
DR. 1 DEC 93 N. Matsubara	DE. 1 DEC 93 N. Matsubara	CHK. S. MANABE	APP. S. MANABE
DR. 13 DEC 93 S. MANABE	DE. 13 DEC 93 S. MANABE	CHK. S. MANABE	APP. S. MANABE